Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
<u>-1</u>	27415	(microgrooves or grooves) same (micron\$1 or millimeters or mm or centimeters or cm or meters or inches)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:43
L2	3197	L1 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:42
L3	2502	L2 and (film or substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:42
L4	13714	(microgrooves or grooves) with (micron\$1 or millimeters or mm or centimeters or cm or meters or inches)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:44
L7	6565	4 and (film or substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:44
L8	1454	L7 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:45
L9	3	L8 and (279/3)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:59
L10	18	L8 and (451/289 or 451/388)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:59
S1	363	(279/3):CCLS:	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/08 06:40
S16	779	((451/289) or (451/388)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:16
S18	443	S16 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:16
S19	243	S18 and (microgroove or groove or slot or hole or apeture)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:17

S20	218	S19 and (holder or plate\$1)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:18
S21	182	S20 and (film or substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:46
S22	1404	(269/21).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:46
523	979	S22 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:46
S24	464	S23 and (film or substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 09:46
S26	129	S24 and (microgroove or groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 10:10
S27	3279	((118/500) or (118/730)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 10:38
S28	1270	S27 and vacuum	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 10:38
S29	1003	S28 and (fil or substrate or wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 12:42
S30	239	S29 and (microgroove or groove)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2005/03/07 10:38